

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	IPG/15/9036	
1.3 Title of PCN	Micro Leadframe Package conversion to High Density for E-Fuse product Family	
1.4 Product Category	Linear Voltage Regulator	
1.5 Issue date	2015-01-21	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Antonio RIVIERA
2.1.3 Quality Manager	Paolo MORETTI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, ...)	CARSEM

4. Description of change

	Old	New
4.1 Description	STD FRAME, Au wire bonding, Molding compound G770HC, Glue for controller die 8006NS	Micro Lead-frame Package (MLP) built on standard Lead-frame will be converted to High Density Lead-frame (HDL) on E-Fuse product family assembled in FPN 3x3mm2 package in Carsem (Suzhou). We grabbed the opportunity to improve the bill of Material too by using a new Glue (HITACHI 4900GCN3) for the Controller Die, the Cu Wire Bonding and an upgraded dedicated molding compound (G770HCD) packaged in a MSL3. The combination of HDL and G770HCD has been already qualified and it is running in production on similar product/packages
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	The HDL implementation will bring to a higher production capability and to a better frame handling that it is translated in a better product quality. On the other hand these changes will harmonize the Bill of Material in CARSEM site.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	see traceability code
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7. Timing / schedule

7.1 Date of qualification results	2014-12-18
7.2 Intended start of delivery	2015-03-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	250-W-14-UW70-STEF05WPUR in VDFPN 3x3-10L (New BOM)-PCN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2015-01-21

9. Attachments (additional documentations)	
9036PpPrdtLst.pdf 250-W-14-UW70-STEF05WPUR in VDFPN 3x3-10L (New BOM)-PCN.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STEF05DPUR	
	STEF05PUR	
	STEF12PUR	

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